

MTM231232LBF

Silicon P-channel MOSFET

For Switching

MTM76123 in SMini3 type package

■ Features

- Low Drain-source On-state Resistance : $R_{DS(on)}$ typ. = $40\text{ m}\Omega$ ($V_{GS} = -4\text{ V}$)
- Low Drive Voltage : 2.5 V Drive
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL : Level 1 compliant)

■ Marking Symbol : BL

■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

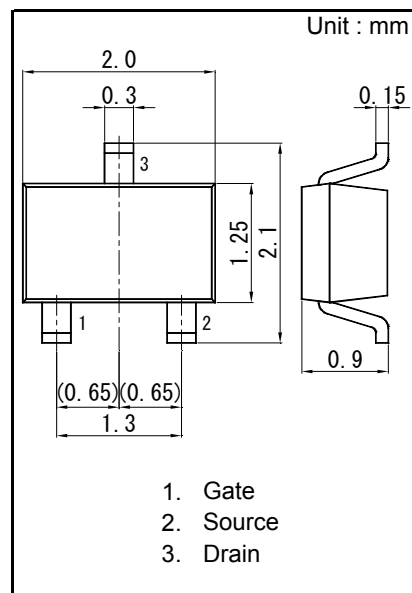
■ Absolute Maximum Ratings $T_a = 25\text{ }^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Drain to Source Voltage	V_{DS}	-20	V
Gate to Source Voltage	V_{GS}	± 10	V
Drain Current	I_D	-3	A
Drain Current (Pulsed) ^{*1}	I_{Dp}	-16	A
Total Power Dissipation ^{*2}	PD	500	mW
Channel Temperature	T_{ch}	150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 to +150	$^\circ\text{C}$

Note ^{*1} Pulse width $\leq 10\text{ }\mu\text{s}$, Duty cycle $\leq 1\%$

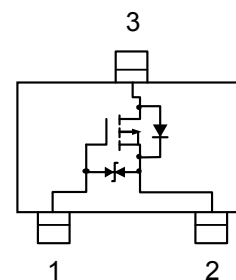
^{*2} Measuring on ceramic board at $40\text{ mm} \times 38\text{ mm} \times 0.1\text{ mm}$.

Absolute maximum rating PD Non-heat sink shall be made 150 mW.



Panasonic	SMini3-G1-B
JEITA	SC-70
Code	SOT-323

Internal Connection



Pin Name

1. Gate
2. Source
3. Drain

■ Electrical Characteristics Ta = 25 °C ± 3 °C

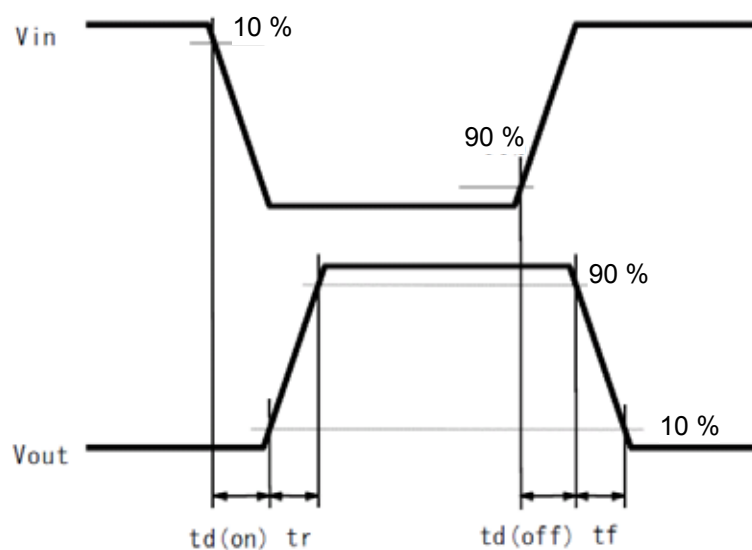
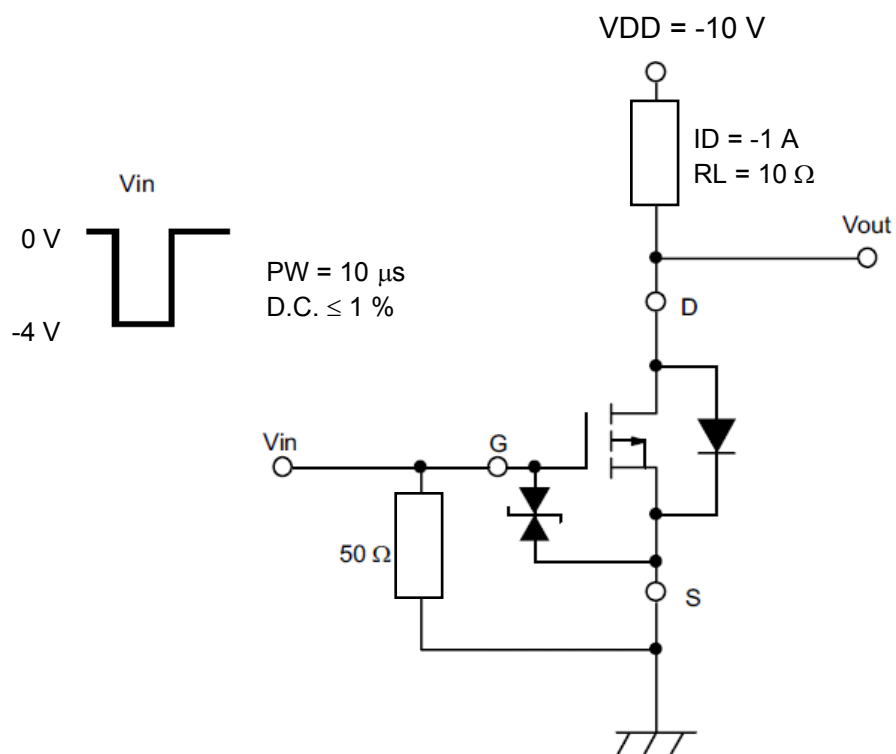
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source Breakdown Voltage	VDSS	ID = -1 mA, VGS = 0 V	-20			V
Zero Gate Voltage Drain Current	IDSS	VDS = -20 V, VGS = 0 V			-1	μA
Gate-source Leakage Current	IGSS	VGS = ±8 V, VDS = 0 V			±10	μA
Gate-source Threshold Voltage	Vth	ID = -1 mA, VDS = -10 V	-0.4	-0.85	-1.3	V
Drain-source On-state Resistance *1	RDS(on)1	ID = -1 A, VGS = -4 V		40	55	mΩ
	RDS(on)2	ID = -0.5 A, VGS = -2.5 V		45	70	
Forward transfer admittance *1	Yfs	ID = -1 A, VDS = -10 V, f = 1 kHz	3.5			S
Input Capacitance	Ciss	VDS = -10 V, VGS = 0 V f = 1 MHz		1 000		pF
Output Capacitance	Coss			120		
Reverse Transfer Capacitance	Crss			120		
Turn-on Delay Time *2	td(on)	VDD = -10 V, VGS = 0 to -4 V		25		ns
Rise Time *2	tr	ID = -1 A		25		
Turn-off Delay Time *2	td(off)	VDD = -10 V, VGS = -4 to 0 V		120		ns
Fall Time *2	tf	ID = -1 A		70		

Note : Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

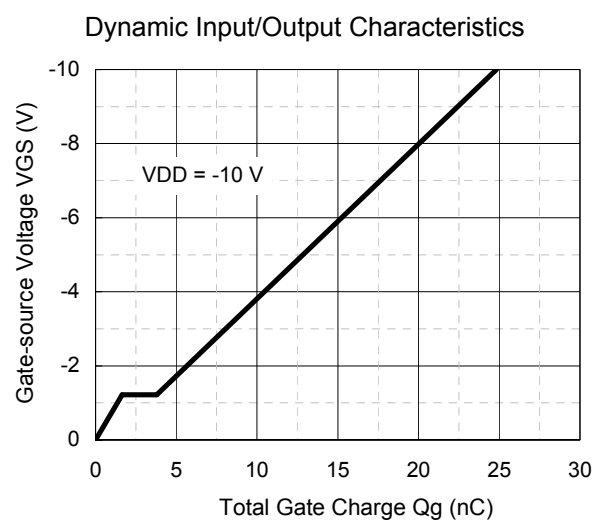
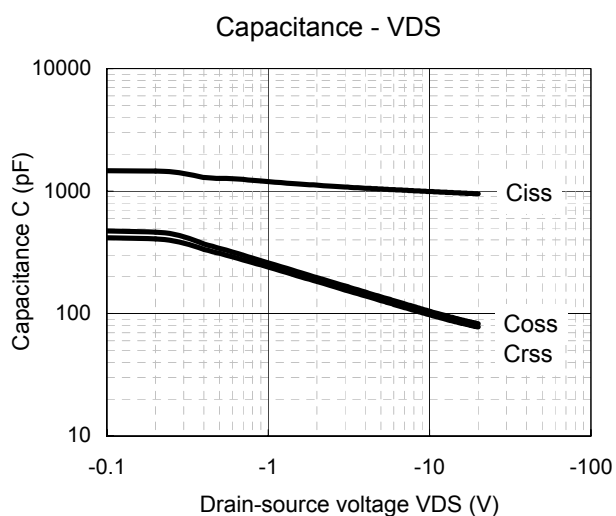
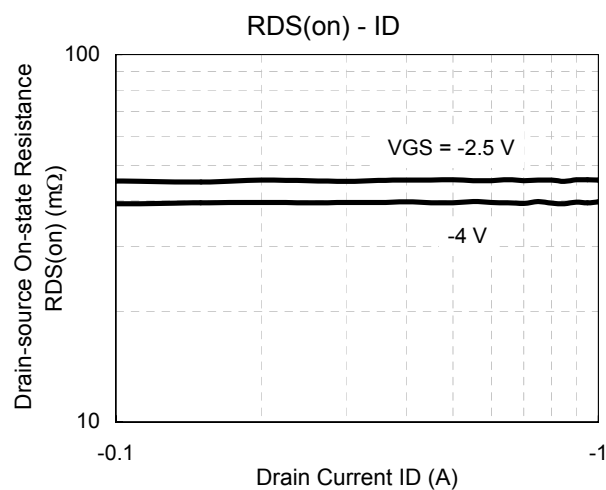
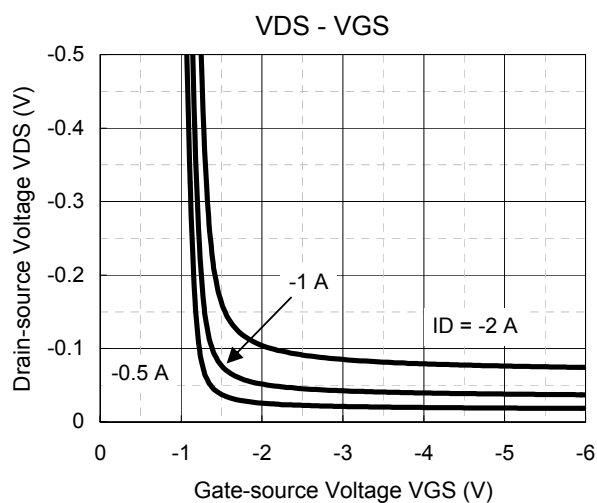
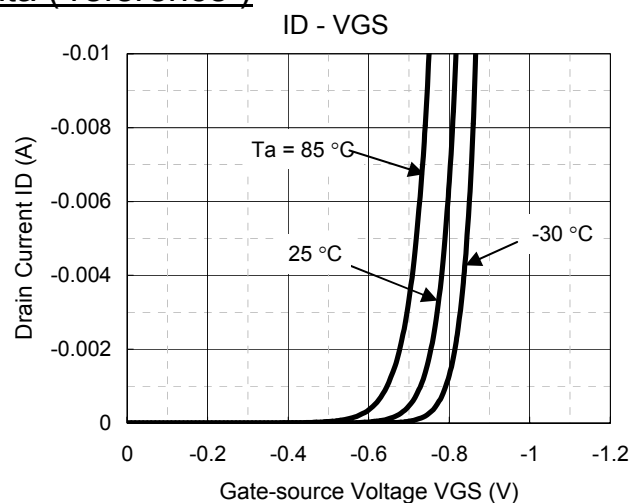
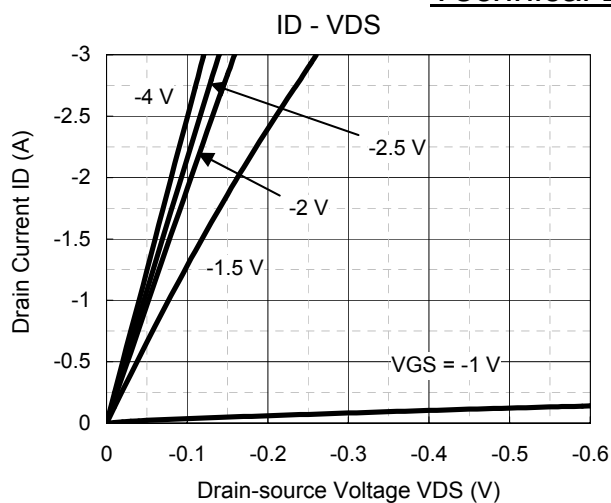
*1 Pulse test : Pulse width ≤ 300 μs, Duty cycle ≤ 2 %

*2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time

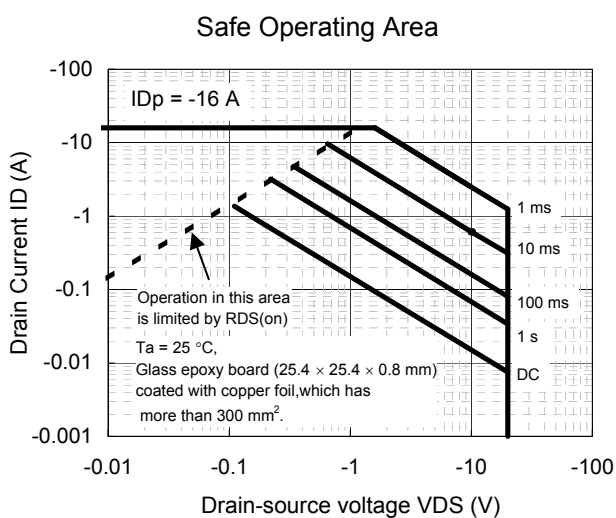
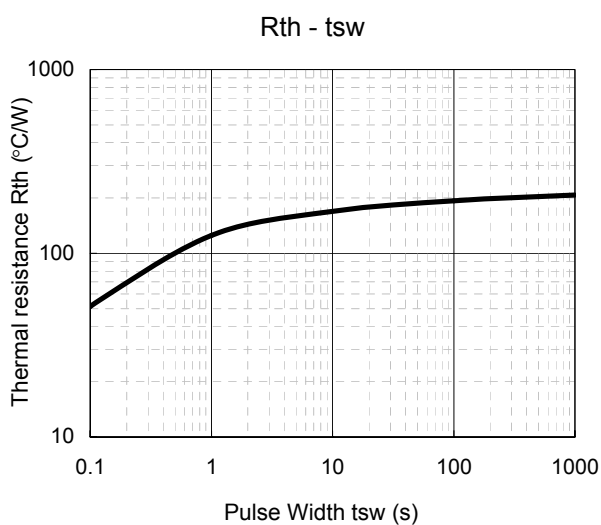
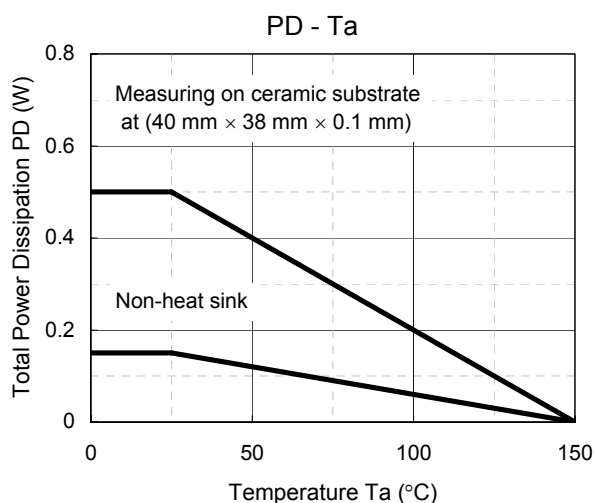
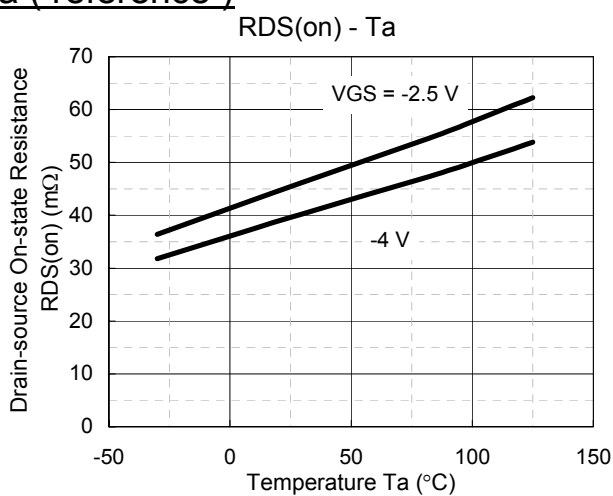
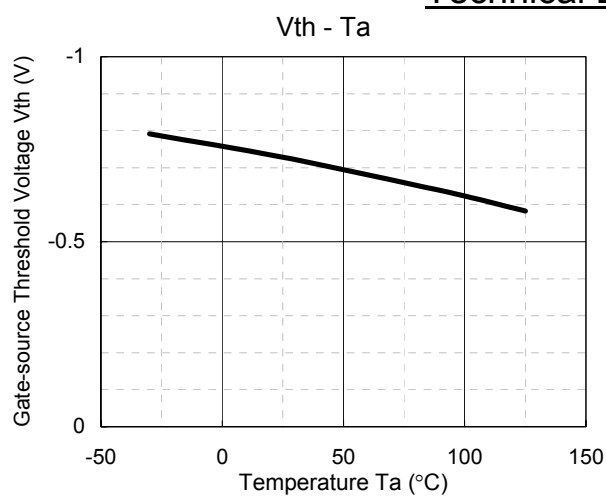
*2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time



Technical Data (reference)



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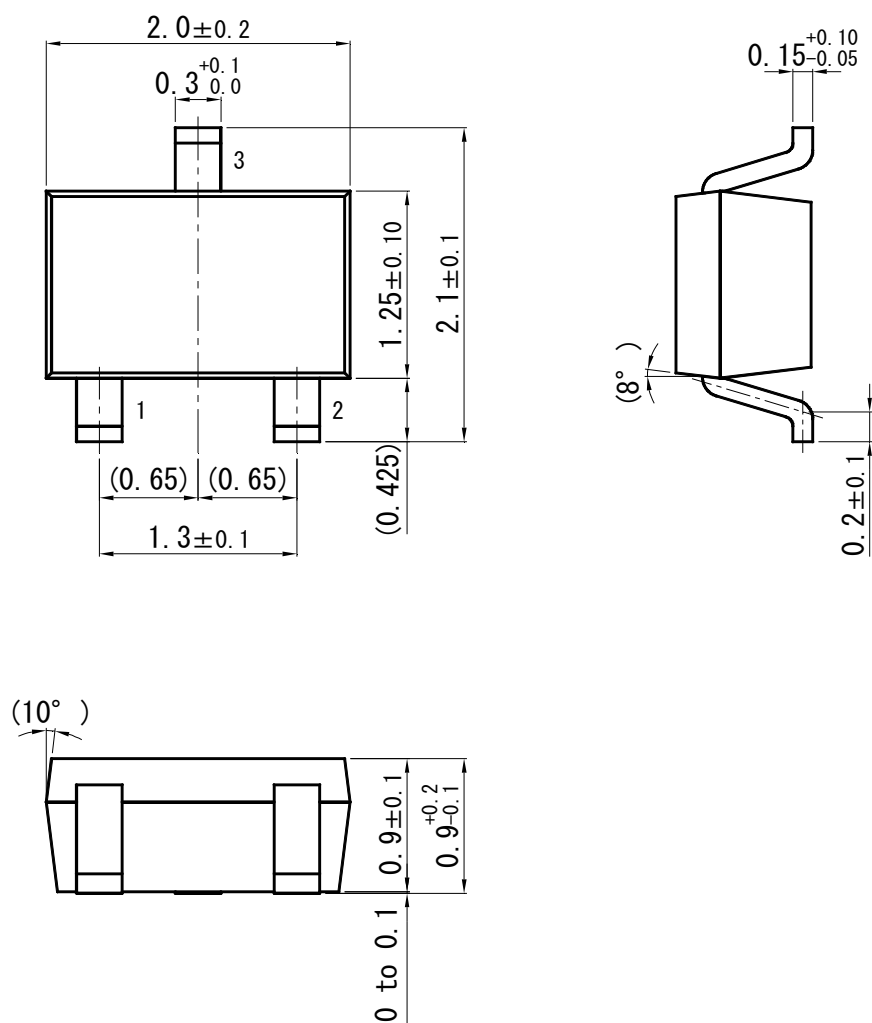


Panasonic

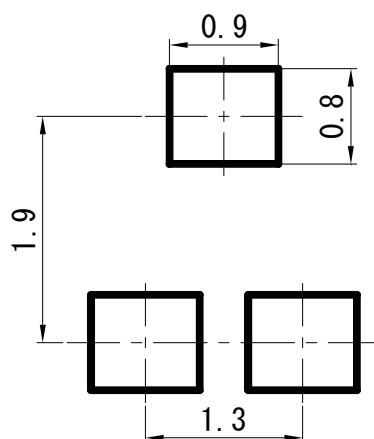
MOS FET
MTM231232LBF

SMini3-G1-B

Unit : mm



■ Land Pattern (Reference) (Unit : mm)



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